μOPALE V2-D

Ultra-dense, low-power Xeon D server-class



■ Ready for OEM with Modified COTS services

ECRIN Systems leverages its deep expertise in server technology to bring customers the first Intel® Xeon® D System-on a-Chip (SoC) solution. μOPALE V2-D offers infrastructure optimization, by combining the performance and advanced intelligence of Intel® Xeon® processors into a dense, lower-power System-on-Chip and SWaP chassis footprint. With server-class reliability, availability and serviceability (RAS) features now available in an ultra-dense, low-power device, μOPALE V2-D will be able to deliver balanced compute, SAN/NAS storage and intelligent edge networks and appliances. These advanced technology building blocks offer the best work load optimized solutions and long life availability with the Intel® Xeon® processor D family with up to 16 cores, 32 threads providing a performance multiply by four improvement, with up to 128GB ECC DDR4 RDIMM operating at 2400MHz, 2x PCle 3.0 x8 full length I/O slots, USB 3.0, up to six SATA 3.0 storage and dual 10 GbE LAN networking ports. μOPALE V2-D, server is optimized for mid-range networking and warm storage environments such as network security appliances, SMB servers with storage, web hosting, controllers, dedicated servers, and other similar applications in harsh Industry and Military/Aerospace environments. We can set you apart from the competitors. ECRIN Systems has a specialized in-house design team that will help customize your server, giving you a unique look that will shape your image and promote your sales. Drop shipping is available to facilitate a rapid, more convenient deployment directly to your end customers.

- > Up to 16-Core / 32-Thread Intel Xeon-D SoC with max TDP of 65W
- > Long life management: up to7 years with revision control
- > Up to 128GB ECC RDIMM DDR4 + 1x socket M.2
- > 2x 10GbE and 2x GbE, 2x USB 3.0 and 4x USB 2.0
- > One dedicated IPMI 2.0 port (virtual media over LAN, KVM-over-LAN support)
- > 2 full-size PCle 8x slots to customize server for your mission
- > Up to Six Hot Swap 2.5" SSD in Rugged Carriers from the front (up to 12 TB)

- > Rear rugged MIL SPEC I/O connectors on demand
- > MIL-STD-810 Shock & Vibration
- > 0-50° operating temperature
- > Complete system monitoring: voltage, temp, airflow to extend long term reliability, watchdog, redundant PSU default, alarm, log file...
- > Single or mini redundant PSU, AC or DC versions
- > Optional front door lockable for security control
- > TPM header for SSI



Rack specifications			
Construction	Anti-corrosion and long term heavy-duty steel		
Dimensions (W x H x D)	19" / 1U with 17.8 inch depth (483x44x450mm)		
Weight	7.5 kg (standard configuration)		
Color	Black		
Cooling	Up to four 40mm ball bearing fans		
	Fan speed regulation and monitoring		
Power supply	1U form factor, compliant with Mini Redundant PSU		
Drive bays	Two 3"1/2 front accessible drive bay		
Motherboard	Mini-ITX : 170 mm x 170 mm		
	2x slots for full length I/O boards (riser)		
Front panel	Front door for drives bays and USB access		
	Mini-IHM, 4 LEDs with I/O capabilities		
Carton size (W x H x D)	620x600x199 mm		
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Option with six 2.5" SSD on front

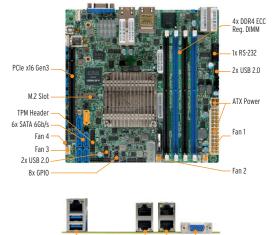




A: 4x tri-color LEDs B: LCD 2x16 characters C: Keyboard (Power & Reset) D: 2x USB 2.0

E: 3"1/2 drive bay F: Single or redundant PSU G: motherboard rear I/O H: 2x PCle x8 slots

Electronic specifications		
Processor	Intel® Xeon® processor D, SoC FCBGA 1667	
BIOS	128Mb SPI Flash with AMI BIOS	
	SMBIOS 2.8, UEFI 2.4, ACPI 5.0	
Memory	Dual channel, Up to 128GB ECC RDIMM DDR4 2400MHz	
	or 64GB ECC/non-ECC UDIMM in 4 sockets	
Video	Aspeed AST2400 - sortie VGA (Rear)	
Ethernet	2 x GbE (Intel® i350-AM2) Rear	
	2x 10GbE (SoC, 10GBase-T) Rear	
	1x Realtek RTL8201N PHY (dedicated IPMI) Rear	
Disk	6x SATA 6Gbps ports - Software RAID 0,1,5,10 RSTe	
	1x socket M.2	
USB	Rear: 2x USB 3.0 connector on the rear	
	2x USB 2.0 pin header + 2 USB 2.0 Front panel	
TPM	TPM header	
IPMI	Support for Intelligent Platform Management Interface v.2.0	
	Virtual media over LAN and KVM-over-LAN support	
1/0	Serial port : 1x RS-232 (pin header)	
	Digital IO : 8x GPIO via onboard feature connector	
PC Health Monitoring	Voltage, Temperature, FAN (x4)	
Expansion Slots	1x PCIe x16 Gen3 - Bifurcation support: 2x PCIe x8	
	1x socket M.2 (PCIe x4 Gen3, SATA, M Key 2242/2280)	



Environmental specifications		
Operating: 0~45°C (MIL STD 810 G, method 502.5 / 501.5) - Storage: -20~80°C		
Operating : 5% to 90% non-condensing		
0-2000m (0-6600ft) operating		
Operating: 20G @ 11ms / 15G @ 20ms - 6 axis (MIL STD 810 G, method. 516.6)		
Operating: 5~7Hz / 10mm, 10~2000Hz / 2G - 3 axis, 2 sweeps, 15min (MIL STD 810 G, method. 514.6)		
43.7 dBA (Iddle), 52.5 dBA (50%), 54.6 dBA (80%) - MIL-STD-740-1		
EMC: 2014/30/UE; EN 61000-6-2, EN55032, EN 55024 - SAFETY: 2014/35/UE; EN60950-1: 2006 2nd edition A11: 2009 + A1: 2010 + A12: 2011 + A2: 2014		

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- > IPMI v2.0 with virtual media and KVM over LAN support
- > Local control with embedded HMI (Windows & Linux services) - Alarm (fan, temperature, redondant P/S),
 - FAN control & monitoring - System & network information

 - Redundant P/S default
 - Watchdog & elapsed time counter
- Log file - User script launch form menu entry
 - - Easy configuration with .TXT file

OEM services

- > Customization:
- Front panel design
- Specific I/O on front panel / rear panel
- Specific H/W configurations
- Specific S/W functionality
- Call us for more information

Standard configuration		Options	
Power Supply Unit	ATX 12V - 300W - High Efficiency 80+	Processor	Intel® Xeon™ D-1587 Processor, 16C/32T, 24Mo, 1.7/2.3 GHz, 65W
	90 ~ 264 VAC full range / 47~63 Hz		Intel® Xeon™ D-1557 Processor, 12C/24T, 18Mo, 1.5/2.1 GHz, TDP 45W
	5V@18A, 12V@22A, -12V@0.5A, 3.3V@16A, 5VSB@2A		Intel® Xeon™ D-1528 Processor, 6C/12T, 9Mo, 1.9/2.5 GHz, TDP 35W
	Option for 2x 220W Redundant 1U P/S		Intel® Xeon™ D-1518 Processor, 4C/8T, 6Mo, 2.2 GHz, TDP 35W
	High Efficiency (80+), 90-264VAC auto range /47-63Hz	Memory	DDR4-2400 ECC Reg. : 4Go ~ 128Go
	5V@16A, 12V@17.5A, -12V@0.3A, 3.3V@16A, 5VSB@2A		DDR4-2400 ECC : 4Go ~ 64Go
Drives	2 x 2.5" SATA Removable Drive Enclosure	Disk	- SLC & MLC Solid State Drive (32 Go ~ 2To)
	1 x 3.5" front accessible drive bay free		- Up to 4x hot swap 2.5" SSD with optional 2 in1 drive bays
Riser	2x PCIe x8 (PCIe x16 connector)		- Up to 6x hot swap 2.5" SSD option three 3.5" front accessible drive bay
Front I/O	2 x USB 2.0	OS	- Microsoft® Windows® 7 32/64-bit, Windows 8.1 & 10 64-bit
Rear I/O	VGA, 2x 10GbE, 2x GbE, 2x USB 3.0 + IPMI		- Linux 32/64-bit

^{*} with SSD

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